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5-203

**PATENT APPLICATION**

**RESPONSE UNDER 37 CFR §1.116  
EXPEDITED PROCEDURE  
TECHNOLOGY CENTER ART UNIT 2825**

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APR 21 2003

TECHNOLOGY CENTER 2800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Akiro SATO

Group Art Unit: 2825

Application No.: 09/424,500

Examiner: G. Lee

Filed: February 22, 2000

Docket No.: 104788

For: METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, MOLDING  
DEVICE FOR SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

**AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116**

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

In reply to the November 19, 2003 Office Action, the period for reply being extended  
by the attached Petition for Extension of Time, please amend the above-identified application  
as follows:

**IN THE CLAIMS:**

Please replace claims 1, 11, 12, 15 and 24 as follows:

1. (Four Times Amended) A method of manufacturing a semiconductor device  
comprising:

placing a semiconductor assembly in which a semiconductor chip is secured to  
a die pad of a lead frame in a cavity of a mold;

applying a pressure in only one direction to the semiconductor assembly;  
least one support pin so as to cause a stress in the lead frame;

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01 FC:1252

300.00 OP

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**PATENT APPLICATION**

**OLIFF & BERRIDGE, PLC**  
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**Alexandria, Virginia 22320**  
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Attorney Docket No.: 104788

**AMENDMENT TRANSMITTAL**

In re the Application of

Akiro SATO

Group Art Unit: 2825

Application No.: 09/424,500

Examiner: G. Lee

Filed: February 22, 2000

For: METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, MOLDING DEVICE FOR SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

Transmitted herewith is an Amendment in the above-identified application.

- ☐ Entitlement to small entity status is hereby asserted.  
☐ Small entity status of this application has been established.

The filing fee has been calculated as shown below:

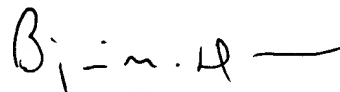
	(Column 1)	(Column 2)	(Column 3)	SMALL ENTITY		OR	OTHER THAN A SMALL ENTITY	
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADD'L FEE		RATE	ADD'L FEE
TOTAL CLAIMS	*30 MINUS	**30	=	x 9	\$		x 18	\$
INDEP CLAIMS	*5 MINUS	***3	=2	x 42	\$		x 84	\$168
<input type="checkbox"/> FIRST PRESENTATION OF MULTIPLE DEP. CLAIM				+ 140	\$	OR	+280	\$
					\$			\$168

- \* If the entry in Column 1 is less than the entry in Column 2, write "0" in Column 3.  
\*\* If the "Highest Number Previously Paid For" IN THIS SPACE is less than 20, write "20" in this space.  
\*\*\* If the "Highest Number Previously Paid For" IN THIS SPACE is less than 3, write "3" in this space.

The "Highest Number Previously Paid For" in this space (Total or Independent) is the highest number found from the equivalent box in Column 1 of a prior Amendment or the number of claims originally filed.

- ☒ Check No. 141475 in the amount of \$168.00 is attached. The Director is hereby authorized to charge any other fees that may be required to complete this filing, or to credit any overpayment, to Deposit Account No. 15-0461. Two duplicate copies of this sheet are attached.

Respectfully submitted,



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Benjamin M. Halpern  
Registration No. 46,494

JAO:BMH/can

Date: April 21, 2003

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